| | ! " # | $ ! % & ' | ! ( ) % * + |
|---|---|---|---|

## / Descriptions

SOT-23 © ª ª « N ¬ - MOS ® ¯ f ° §
N-CHANNEL MOSFET in a SOT-23 Plastic Package.

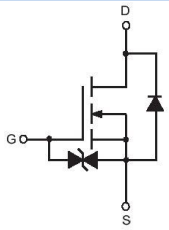
## / Features

± ² % ³ - ` ´ µ ¶ · ¸ ¹ º % » ¢ ¶ · § ¼ ¶ ½ ¾ ¿ 2KV C n o AEC-Q101 p q T r s t u v C À Á i j §
Sensitive gate trigger current and Low Holding current.ESD protected up to 2KV, Qualified to AEC-Q101 Standards for High Reliability, HF Product.

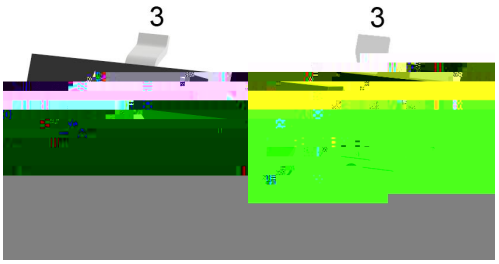
## / Applications

L Â Ã Ä % Å Æ ¸ Ç S ³ - C w x g h f L % y A u v §
Intended for use in general purpose switching and phase control applications, Meet the stringent requirements of automotive applications.

## / Equivalent Circuit




## / Pinning



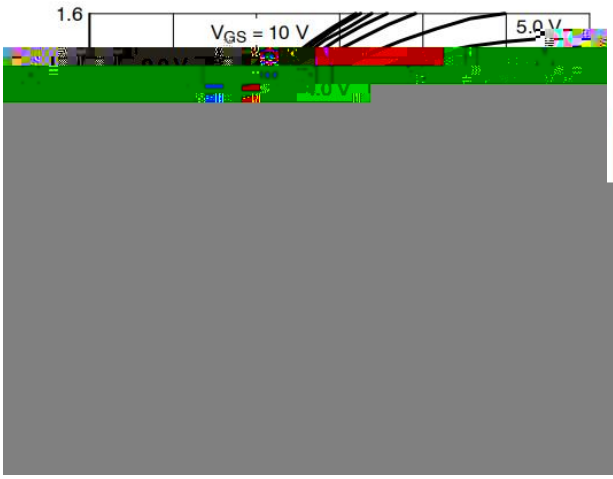

PIN1 ¦ G PIN 2 ¦ S PIN 3 ¦ D

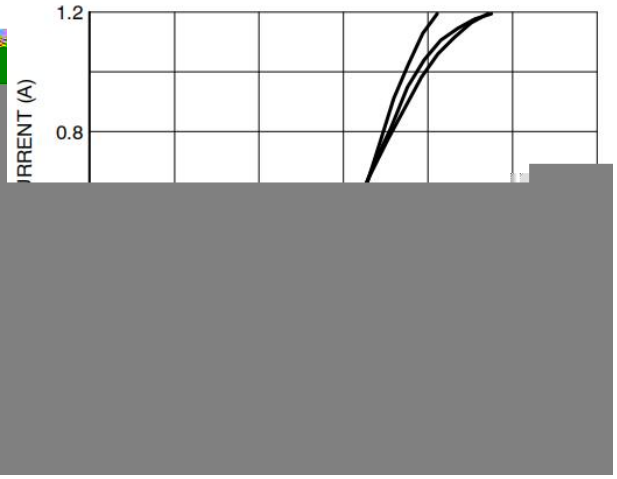
## / Marking

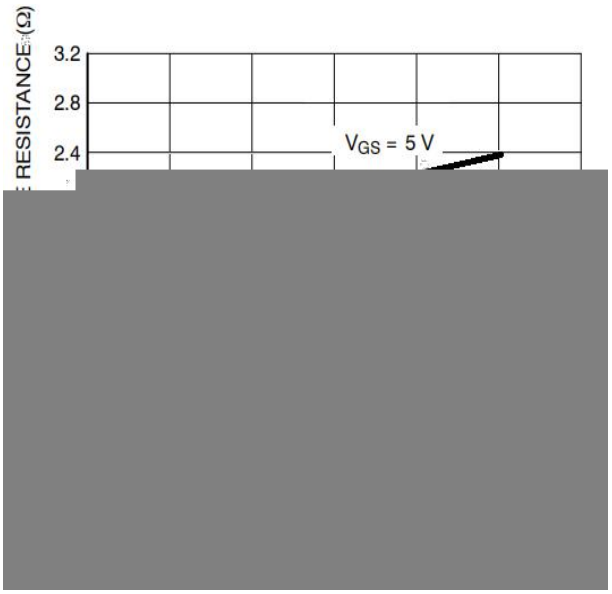
| | |
|---|---|
| Marking | 702Q2 |

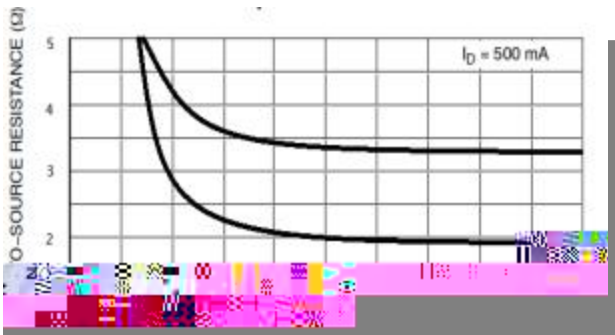
| Parameter | Symbol | Test Conditions | Min | Typ | Max | Unit |
|---|---|---|---|---|---|---|
| Turn－On Delay Time | $t_{d(ON)}$ | | | 12.2 | | |
| Rise Time | t | VGS =10V, VDD=25V, ID=500mA, RG=25Ω | | | | ns |

## / Electrical Characteristic Curve



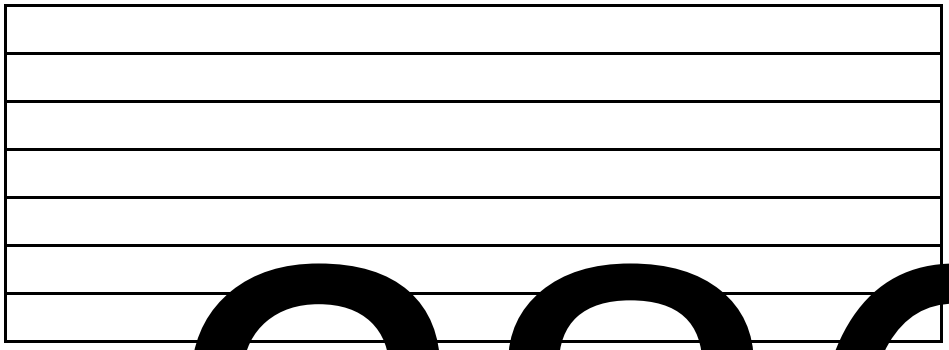



**BR2N7002K2Q**
Revl

**B**



## ( ) / Temperature Profile for IR Reflow Soldering(Pb-Free)



说明：

1、预热温度 150～200 ，时间 60 sec;

2、峰值温度 255 5 ，时间持 5 0.5sec;

3、焊接制程冷却速度为 2～ /sec.

Not

1.P eating:150~ , Ti 0~120sec.

2. k Temp.:255 , Dura :5 0.5sec.

3. C ng Speed: 0 /sec.

## / Resistance to Soldering Heat Test Conditions

温度：260 5



39.509 TD [( )]TJ ET BT 10.56 0 0 10.56 0 0 1m /F8 1 Tf 0 0 0 sc 00 0 SC 0 Tr 18.262 46.327 TD [( " )]TJ ET BT 10.56 0